

High Voltage IGBTFor Capacitor Discharge Applications

(Electrically Isolated Tab)

IXGF25N300

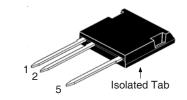


 $V_{CES} = 3000V$ $I_{C25} = 27A$ $V_{CF(sat)} \le 3.0V$

Symbol	Test Conditions	Maximum Ratings		
V _{CES}	T _J = 25°C to 150°C	3000	V	
$\mathbf{V}_{\mathtt{CGR}}$	$T_{_{\mathrm{J}}} = 25^{\circ}\text{C} \text{ to } 150^{\circ}\text{C}, R_{_{\mathrm{GE}}} = 1\text{M}\Omega$	3000	V	
V _{GES}	Continuous	± 20	V	
V _{GEM}	Transient	± 30	V	
I _{C25}	$T_{c} = 25^{\circ}C$	27	A	
I _{C90}	$T_{c} = 90^{\circ}C$	16	Α	
I _{CM}	$T_{_{\rm C}} = 25^{\circ}{\rm C}, V_{_{\rm GE}} = 20{\rm V}, 1{\rm ms}$	140	Α	
SSOA	$V_{GE} = 20V, T_{VJ} = 125^{\circ}C, R_{G} = 5\Omega$	I _{CM} = 160	Α	
(RBSOA)	Clamped Inductive Load	$V_{CE} \le 0.8 \bullet V_{CES}$		
P _c	T _c = 25°C	114	W	
T _J		-55 +150	°C	
T_{JM}		150	°C	
T _{stg}		-55 +150	°C	
T _L T _{SOLD}	1.6 mm (0.062 in.) from Case for 10s Plastic Body for 10s	300 260	°C °C	
F _c	Mounting Force	20120/4.527	Nm/lb-in.	
V _{ISOL}	50/60Hz, 1 Minute	4000	V~	
Weight		5	g	

Symbol (T _J = 25°C	Test Conditions , Unless Otherwise Specified)	Chara Min.	cteristi Typ.		
BV _{CES}	$I_{\rm C}=1{\rm mA},V_{\rm GE}=0{\rm V}$	3000			V
V _{GE(th)}	$I_{C} = 250\mu A, V_{CE} = V_{GE}$	3.0		5.0	V
I _{CES}	$V_{CE} = 0.8 \bullet V_{CES}, V_{GE} = 0V$ Note 2, $T_{J} = 0$	125°C		50 1	μA mA
I _{GES}	$V_{CE} = 0V, V_{GE} = \pm 20V$			±100	nA
V _{CE(sat)}	$I_{c} = 25A, V_{GE} = 15V, Note 1$ $I_{c} = 75A$			3.0 5.5	V

ISOPLUS i4-Pak™



1 = Gate 5 = Collector 2 = Emitter

Features

- Silicon Chip on Direct-Copper Bond (DCB) Substrate
- Isolated Mounting Surface
- 4000V Electrical Isolation
- High Peak Current Capability
- Low Saturation Voltage
- Molding Epoxies Meet UL 94 V-0 Flammability Classification

Applications

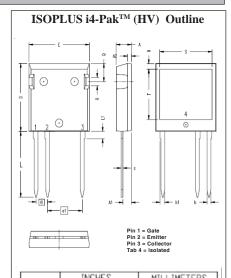
- Capacitor Discharge
- Pulser Circuits

Advantages

- High Power Density
- Easy to Mount



Symbol Test Conditions		Characteristic Values			
$(T_J = 25)$	5°C, L	Inless Otherwise Specified)	Min.	Тур.	Max.
g _{fs}		$I_{\rm C} = 50$ A, $V_{\rm CE} = 10$ V, Note 1	16	26	S
I _{C(ON)}		$V_{GE} = 15V$, $V_{CE} = 20V$, Note 1		240	А
C _{ies})			2970	pF
\mathbf{C}_{oes}	}	$V_{CE} = 15V, V_{GE} = 20V, f = 1MHz$		98	pF
C _{res}				36	pF
$\mathbf{Q}_{\mathrm{g(on)}}$)			75	nC
\mathbf{Q}_{ge}	}	$I_{_{\mathrm{C}}} = 50 \mathrm{A}, \ V_{_{\mathrm{GE}}} = 15 \mathrm{V}, \ V_{_{\mathrm{CE}}} = 0.5 \bullet \mathrm{V}_{_{\mathrm{CES}}}$		15	nC
\mathbf{Q}_{gc}				30	nC
t _{d(on)})	Resistive Switching Times		70	ns
t,		I _C = 25A, V _{GE} = 15V		240	ns
$\mathbf{t}_{d(off)}$	($V_{CE} = 1500V, R_{e} = 150$		220	ns
t _f		CE 10001, 1.G		500	ns
R_{thJC}					1.10 °C/W
H_{thCS}				0.15	°C/W
R _{thJA}				30	°C/W



MYZ	INCHES		MILLIMETERS		
214	MIN	MAX	MIN	MAX	
Α	.190	.205	4.83	5.21	
A1	.102	.118	2.59	3.00	
A2	.046	.085	1.17	2.16	
b	.045	.055	1.14	1.40	
b1	.058	.068	1.47	1.73	
С	.020	.029	0.51	0.74	
D	.819	.840	20.80	21.34	
Ε	.770	.799	19.56	20.29	
е	.150 BSC		3.81 BSC		
e1	.450BSC		11.43	BSC	
L	.780	.840	19.81	21.34	
L1	.083	.102	2.11	2.59	
Q	.210	.244	5.33	6.20	
R S	.100	.180	2.54	4.57	
S	.660	.690	16.76	17.53	
Т	.590	.620	14.99	15.75	
U	.065	.080	1.65	2.03	

Notes:

- 1. Pulse test, $t < 300\mu s$, duty cycle, d < 2%.
- 2. Device must be heatsunk for high-temperature leakage current measurements to avoid thermal runaway.

